

DMG1016V COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage V_{GS(th)} <1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- ESD Protected Gate to 2.5kV HBM
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 7
- Ordering Information: See Page 7
- Weight: 0.006 grams (approximate)

ESD PROTECTED TO 2.5kV HBM

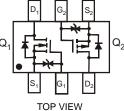


TOP VIEW



SOT-563

BOTTOM VIEW



Internal Schematic

Maximum Ratings N-CHANNEL – Q_1 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	20	V
Gate-Source Voltage	V _{GSS}	±6	V
Drain Current (Note 1) $T_A = 25^{\circ}$ $T_A = 85^{\circ}$		870 630	mA

Maximum Ratings P-CHANNEL – Q_2 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	-20	V
Gate-Source Voltage	V _{GSS}	±6	V
Drain Current (Note 1) $T_A = 25$ $T_A = 85$		-640 -460	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	530	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	235	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes: 1. Device mounted on FR-4 PCB.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.



Electrical Characteristics N-CHANNEL – Q_1 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I _{DSS}			100	nA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	± 1.0	μΑ	$V_{GS} = \pm 4.5 V, V_{DS} = 0 V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	V _{GS(th)}	0.5	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
	5	_	0.3	0.4		$V_{GS} = 4.5V, I_D = 600mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	0.4 0.5	0.5 0.7	Ω	$V_{GS} = 2.5V, I_D = 500mA$ $V_{GS} = 1.8V, I_D = 350mA$
Forward Transfer Admittance	Y _{fs}	_	1.4	_	S	$V_{DS} = 10V, I_D = 400 \text{mA}$
Diode Forward Voltage (Note 4)	V _{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$
DYNAMIC CHARACTERISTICS					•	
Input Capacitance	Ciss		60.67		pF	
Output Capacitance	C _{oss}		9.68	_	pF	V _{DS} = 16V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	5.37	—	pF	1 = 1.00012
Total Gate Charge	Qg	_	736.6	—		
Gate-Source Charge	Q _{gs}		93.6		рС	$V_{GS} = 4.5V, V_{DS} = 10V,$ In = 250mA
Gate-Drain Charge	Q _{gd}		116.6			ID = 230IIIA
Turn-On Delay Time	t _{d(on)}	_	5.1	_		
Turn-On Rise Time	tr	_	7.4	—	200	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 47\Omega, R_{G} = 10\Omega,$
Turn-Off Delay Time	t _{d(off)}		26.7	—	ns	$R_L = 4752, R_G = 1052,$ $I_D = 200 \text{mA}$
Turn-Off Fall Time	t _f		12.3	—		

Electrical Characteristics P-CHANNEL – Q_2 @T_A = 25°C unless otherwise specified

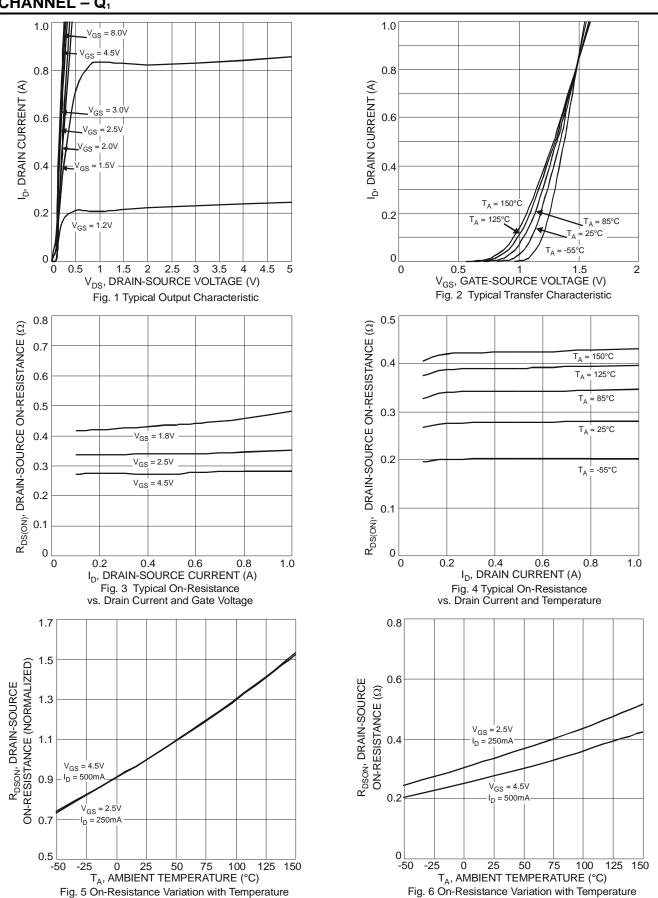
Characteristic	Symbol	Mim	Turn	Mey	ا ا سال	Test Condition
	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)			1	r	-	r
Drain-Source Breakdown Voltage	BV _{DSS}	-20			V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}			-100	nA	V_{DS} = -20V, V_{GS} = 0V
Gate-Source Leakage	I _{GSS}	_		± 2.0	μA	$V_{GS} = \pm 4.5 V$, $V_{DS} = 0 V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	V _{GS(th)}	-0.5		-1.0	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Citatia Dasia Course On Desistence		_	0.5	0.7	Ω	$V_{GS} = -4.5V, I_D = -430mA$
Static Drain-Source On-Resistance	R _{DS (ON)}		0.7 1.0	0.9 1.3		$V_{GS} = -2.5V, I_D = -300mA$ $V_{GS} = -1.8V, I_D = -150mA$
Forward Transfer Admittance	Y _{fs}	_	-0.9	_	S	$V_{DS} = 10V, I_D = -250mA$
Diode Forward Voltage (Note 4)	V _{SD}		-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -150mA$
DYNAMIC CHARACTERISTICS					_	
Input Capacitance	C _{iss}	_	59.76	_	pF	
Output Capacitance	C _{oss}	_	12.07	_	pF	V _{DS} = -16V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	6.36	_	pF	1 = 1.01011Z
Total Gate Charge	Qg	_	622.4	_		
Gate-Source Charge	Q _{gs}	_	100.3	_	рС	$V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -250mA$
Gate-Drain Charge	Q _{gd}	_	132.2	_		ID = -20011A
Turn-On Delay Time	t _{d(on)}		5.1			
Turn-On Rise Time	tr	_	8.1	_	ns	$V_{DD} = -10V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t _{d(off)}	_	28.4	_	115	$R_L = 47\Omega, R_G = 10\Omega,$ $I_D = -200mA$
Turn-Off Fall Time	t _f	_	20.7	_		

Notes: 4. Short duration pulse test used to minimize self-heating effect.



N-CHANNEL – Q₁

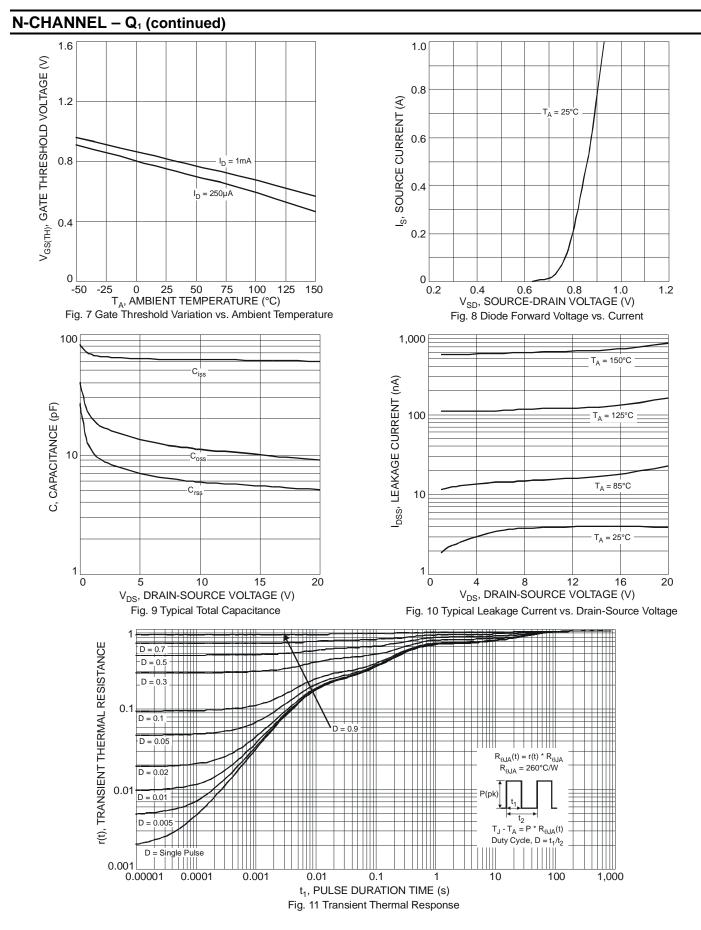
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DMG1016V

3.0

1.0

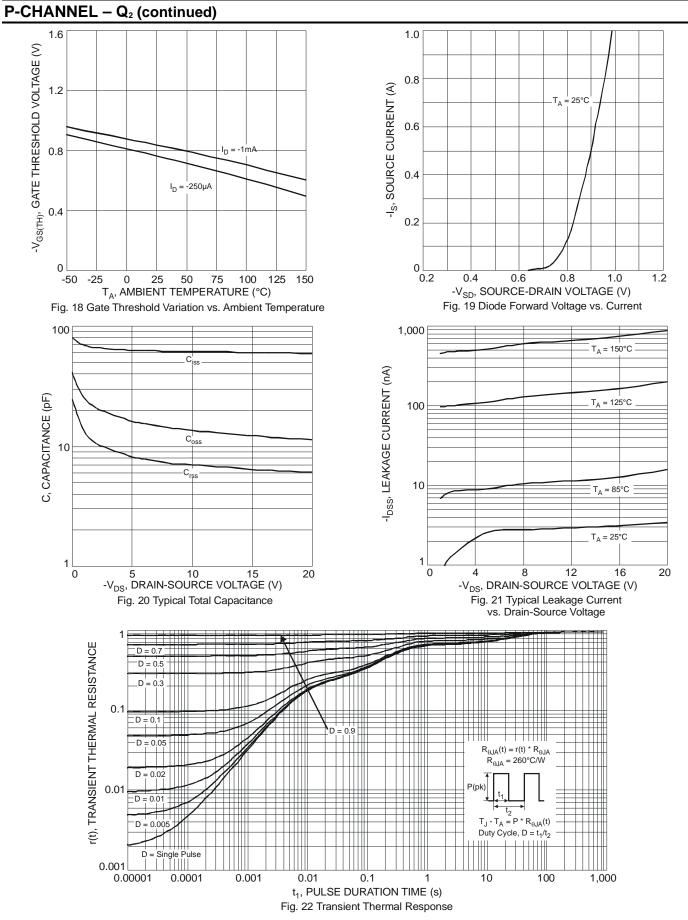
P-CHANNEL – Q₂ 1.0 1.0 $V_{GS} = -8.0V$ V_{GS} = -4.5V $V_{DS} = -5V$ 0.8 0.8 -I_D, DRAIN CURRENT (A) -3.0\ 0.6 0.6 -2.5\ GS -2.0V 0.4 0.4 T_A = 1[']50°C 0.2 0.2 -1.5\ 'GS $T_A = 125^{\circ}C$ T_A = 85°C = 25°C A -55°C T_A = 0 0 ō 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5 0 0.5 1.0 1.5 2.0 2.5 -V_{DS}, DRAIN-SOURCE VOLTAGE (V) -V_{GS}, GATE-SOURCE VOLTAGE (V) Fig. 13 Typical Transfer Characteristic Fig. 12 Typical Output Characteristic 1.6 1.0 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (Ω) 0 70 70 70 70 70 70 70 $R_{\text{DS}(\text{ON})},$ DRAIN-SOURCE ON-RESISTANCE (Ω) -4.5 V_{GS} = 1.4 $T_{A} = 150^{\circ}C$ 1.2 = -1.8V V_{GS} T_A = 125°C 1.0 $T_A = 85^{\circ}C$ 0.8 $T_A = 25^{\circ}C$ V_{GS} = -2.5V 0.6 $T_A = -55^{\circ}C$ 0.4 V_{GS} = -4.5V 0.2 0 0 0 0.4 0 0.2 0.6 0.8 1.0 0.2 0.4 0.6 0.8 -I_D, DRAIN-SOURCE CURRENT (A) Fig. 14 Typical On-Resistance -I_D, DRAIN CURRENT (A) Fig. 15 Typical On-Resistance vs. Drain Current and Gate Voltage vs. Drain Current and Temperature 1.7 1.0 R_{DSON} , DRAIN-SOURCE ON-RESISTANCE (Ω) 1.5 R_{DSON}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 0.8 $V_{GS} = -2.5V$, -250mA I_D 1.3 0.6 1.1 V_{GS} = -4.5V V_{GS} = -4.5V 0.4 I_D = -500mA I_D = -500mA 0.9 0.2 V_{GS} = -2.5V 0.7 I_D = -250mA 0.5 0 125 150 -50 -25 25 75 100 50 0 -50 -25 0 25 50 75 100 125 150 T_A, AMBIENT TEMPERATURE (°C) T_A, AMBIENT TEMPERATURE (°C) Fig. 16 On-Resistance Variation with Temperature Fig. 17 On-Resistance Variation with Temperature

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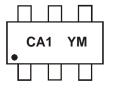


Ordering Information (Note 5)

Part Number	Case	Packaging
DMG1016V-7	SOT-563	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information

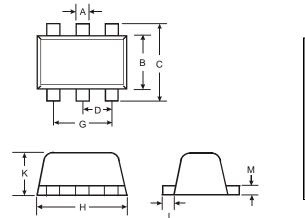


CA1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

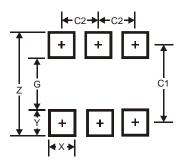
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Y		Ζ	А		В		С
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Package Outline Dimensions



SOT-563							
Dim	Min	Min Max					
Α	0.15	0.30	0.20				
В	1.10	1.25	1.20				
С	C 1.55 1.70 1.6						
D	-	-	0.50				
G	0.90	1.10	1.00				
H 1.50 1.70 1.6							
K 0.55 0.60 0.60							
L	0.10	0.30	0.20				
М	0.10	0.18	0.11				
All	Dimens	sions in	mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5

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